

ABSTRACT

In the application of dry film solder mask material to a board (16), a process and an applicator (10) for the implementation thereof features automatic feed of the board, initiation of leading and trailing edge tacking, by heated or unheated tacking rolls (28,30) of the film (36,46) to the board by utilization of the board to apply a force tangential to the tacking rolls, and logic circuitry to regulate the leading and trailing edge tacking by closing the tacking rolls to apply roll pressure during each of the leading and trailing edge tacks, and after tacking of the film to the leading edge of the board, opening of the rolls to allow the film to be applied without pressure with the rolls being closed again to tack the film to the trailing edge of the board.

This Sheet Has Been Replaced

